

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. – 10. (canceled)

11. (currently amended) A semiconductor integrated circuit device for use with a solid state image pickup device, the semiconductor integrated circuit device comprising:

_____ a correlated double sampling amplifier which receives an image signal from the solid state image pickup device and amplifies a difference voltage between a black level in a feedthrough period of the solid state image pickup device and a signal level in a charge signal output period,

_____ a gain control amplifier which receives an output signal from the correlated double sampling amplifier and amplifies the output signal from the correlated double sampling amplifier, an A/D converter which receives an output signal from the gain control amplifier and converts the output signal from the gain control amplifier to a digital video signal,

_____ an offset cancelling circuit which applies an offset cancelling voltage for cancelling an offset voltage corresponding to an offset in regard to an output of the solid state image pickup device to an input terminal of the correlated double sampling amplifier; and
A semiconductor integrated circuit device according to Claim 1, further comprising:

a correction circuit which detects the difference voltage between the black level in the feedthrough period of the solid state image pickup device in the state where the solid state image pickup device is optically interrupted and the signal level in the charge signal output period where the solid state image pickup device is optically interrupted, generates a feedback clamp voltage based on the detected difference voltage, and then applies the feedback clamp voltage to a signal line between the correlated double sampling amplifier and the A/D converter.